IEC 62769-103-4

Edition 2.0 2020-04

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Field device integration (FDI) – Part 103-4: Profiles – PROFINET

Intégration des appareils de terrain (FDI) – Partie 103-4: Profils – PROFINET



IEC 62769-103-4:2020-04(en-fr)

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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CONTENTS

FOREWORD 4
1 Scope 6
2 Normative references 6
3 Terms, definitions, abbreviated terms and conventions 7
3.1 Terms and definitions 7
3.2 Abbreviated terms 7
3.3 Conventions 7
3.3.1 EDDL syntax 7
3.3.2 XML syntax 7
3.3.3 Capitalizations 7
4 Profile for PROFINET 8
4.1 General 8
4.2 Catalog profile 8
4.2.1 Protocol support file 8
4.2.2 CommunicationProfile definition 9
4.2.3 Profile device 9
4.2.4 Protocol version information 9
4.3 Associating a Package with a device 10
4.3.1 Device type identification mapping 10
4.3.2 Device type revision mapping 11
4.4 Information Model mapping 12
4.4.1 ProtocolType definition 12
4.4.2 DeviceType mapping 12
4.4.3 FunctionalGroup identification definition 13
4.5 Topology elements 13
4.5.1 ConnectionPoint definition 13
4.5.2 Communication Device definition 15
4.5.3 Communication service provider definition 16
4.5.4 Network definition 17
4.6 Methods 17
4.6.1 Methods for FDI Communication Servers 17
4.6.2 Methods for Gateways 21
Annex A (normative) Topology scan schema 28
A.1 General 28
A.2 Network 28
A.3 ProfinetNetworkT 28
A.4 ProfinetConnectionPointT 28
A.5 ProfinetIdentificationT 29
A.6 MACT 30
A.7 IPv4T 30
A.8 IPv6T 30
A.9 DNSNameT 30
A.10 Hex4DigitT 30
Annex B (normative) Transfer service parameters 31
B.1 General 31
B.2 sendData 31

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B.3 receiveData 31
B.4 TransferSendDataT 31
B.5 TransferResultDataT 32
B.6 OperationT 32
Bibliography 33

Figure 1 – Version mapping problem 11

Table 1 – ProtocolSupportFile for FDI Device Packages 8
Table 2 – ProtocolSupportFile for FDI Communication Packages 9
Table 3 – Catalog values for profile devices 9
Table 4 – Version mapping examples 10
Table 5 – Device identification information mapping 11
Table 6 – Protocol type Profinet_IO 12
Table 7 – DeviceType Property mapping 13
Table 8 – PROFINET identification type definition 13
Table 9 – ConnectionPoint type for Profinet_IO 14
Table 10 – Method Connect arguments 18
Table 11 – Method Disconnect arguments 18
Table 12 – Method Transfer arguments 19
Table 13 – Method SetAddress arguments 20
Table 14 – Method Connect arguments 22
Table 15 – Method Transfer arguments 23
Table 16 – Method SetAddress arguments 25
Table A.1 – Elements of ProfinetNetworkT 28
Table A.2 – Attributes of ProfinetConnectionPointT 29
Table A.3 – Elements of ProfinetConnectionPointT 29
Table A.4 – Attributes of ProfinetIdentificationT 29
Table B.1 – Attributes of TransferSendDataT 32
Table B.2 – Attributes of TransferResultDataT 32

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FIELD DEVICE INTEGRATION (FDI) –

Part 103-4: Profiles – PROFINET

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International Standard IEC 62769-103-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) support for generic protocol extension for faster adoption of other technologies;
b) support for Package Developers to build EDDs targeted for today's EDD bases system under a single development tool.

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The text of this International Standard is based on the following documents:

CDV	Report on voting
65E/623/CDV	65E/686A/RVC 65E/686/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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FIELD DEVICE INTEGRATION (FDI) –

Part 103-4: Profiles – PROFINET

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1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-2_CP 3/4, IEC 61784-2_CP3/5 and IEC 61784-2_CP3/6 (PROFINET[1]).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-5-10, *Industrial communication networks - Fieldbus specifications - Part 5-10: Application layer service definition - Type 10 elements*

IEC 61784-2, *Industrial communication networks - Profiles - Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC Unified Architecture - Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) - Part 2: FDI Client*

IEC 62769-4, *Field Device Integration (FDI) - Part 4: FDI Packages*

IEC 62769-5, *Field Device Integration (FDI) - Part 5: FDI Information Model*

IEC 62769-6, *Field Device Integration (FDI) - Part 6: FDI Technology Mapping*

IEC 62769-7, *Field Device Integration (FDI) - Part 7: FDI Communication Devices*

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD;* available at <www.PROFIBUS.com>

PI Order No.: 2.352:2014, *GSDML Specification for PROFINET IO;* available at <www.profibus.com>

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